

SUBSTRATE POLISHING APPARATUS AND  
SUBSTRATE POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

A substrate polishing apparatus wherein semiconductor  
5 substrate is held by a top ring 10-2 or 11-2 and is pressed  
against a polishing surface of a polishing table 10-1 or  
10-2. A surface to be polished of the semiconductor  
substrate is polished by a relative movement between the  
semiconductor substrate and the polishing surface. The  
10 apparatus includes pressing force changing mechanism for  
changing an pressing force for pressing the semiconductor  
substrate, relative movement seed changing mechanism for  
changing the number of revolutions of the top ring and/or  
the polishing table, and control mechanism. The control  
15 mechanism performs the polishing through plural polishing  
processes on the polishing table 10-1 or 10-2 while  
changing the pressing force and the number of revolutions.